



MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN #: ASER-22ORME994

**Date:
November 15, 2022**

Qualification of 2035SCR as a new die attach material for selected ATA5577M1330C-PAE and AT88SC6416CRF-MR2 catalog part numbers (CPN) available in SCC (5.06x8x0.38 mm) package assembled at LITH.

Purpose: Qualification of 2035SCR as a new die attach material for selected ATA5577M1330C-PAE and AT88SC6416CRF-MR2 catalog part numbers (CPN) available in SCC (5.06x8x0.38 mm) package assembled at LITH.

CCB: 5354

<u>Misc.</u>	Assembly site	LITH
	BD Number	BD-001243-01
	MP Code (MPC)	56903SHCBCL2
	CPN	AT88SC6416CRF-MR2
	Assembly Shipping Media (T/R, Tube/Tray)	T&R
	Base Quantity Multiple (units per Tray/Tube/T&R)	9K
<u>Lead-Frame</u>	Paddle size	3.4 x 3.7 mm
	Material (C194, C7025)	CuSn6
	DAP Surface Prep (Ring, Double Ring)	Ag Plated
	Treatment (Roughened, Non-Rough)	Roughened
	Process (Stamped, Etched)	Stamped
	Lead-lock (yes or no)	Yes
	Part Number	XOA2
	Lead Plating	Ag
	Strip Size	37 ± 0.05 mm
	Strip Density	3 rows, x-pitch: 9,5 mm
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	2035SCR
	Conductive (Yes or No)	No
<u>MC</u>	Part Number	GE-880
<u>PKG</u>	PKG Type	SCC
	Pin/Ball Count	0
	PKG width/size	5.06 x 8 x 0.38 mm

Test Item	Conditions	Duration	Sample Size	Qty of Lots	Total Units	Fail Accept Qty	ATE Test Site	REL Test Site
1	WBS JESD22-B116/AEC-Q100 (ball shear)		5	3	15	0		
2	WBP MIL-STD-883-2011 (ball pull)		5	3	15	0		
3	THB JESD22-A101 (85°C / 85%rH / 168h; Tm=RT)	168hrs	77	3	231	0	LITH	LITH
4	TCT JESD22-A104 (-25°C / 85°C / 200x; Tm=RT)	200Cy	77	3	231	0	LITH	LITH
5	HTSL JESD22-A103 (Ts=85°C / 168h; Tm=RT)	168hrs	77	3	231	0	LITH	LITH

ASER-22ORME994 - CCB 5354 Initial Notice: Qualification of 2035SCR as a new die attach material for selected ATA5577M1330C-PAE and AT88SC6416CRF-MR2 catalog part numbers (CPN) available in SCC (5.06x8x0.38 mm) package assembled at LITH.

Affected Catalog Part Numbers (CPN)

ATA5577M1330C-PAE

AT88SC6416CRF-MR2